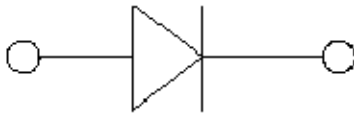


Small Signal Schottky Diode

Features

- V_R 40V/30V/20V
- I_{FAV} 350mA



Mechanical Data

- **Package:** SOD-323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

	Marking
SD103AWS	S4
SD103BWS	S5
SD103CWS	S6

■ Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Reverse voltage	V_R	V	$I_R=100\mu A$	SD103AWS	40
				SD103BWS	30
				SD103CWS	20
Peak forward surge current	I_{FSM}	A	$t_p=8.3ms$, half sine	1.5	
Average forward current	I_{FAV}	mA	$T_c=25^\circ C$	350	
Power dissipation	P_D	mW		200	
Junction temperature	T_j	$^\circ C$		-55 to +125	
Storage temperature range	T_{stg}	$^\circ C$		-55 to +150	
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	$^\circ C/W$		500	

■ Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Maximum Forward voltage	V_F	V	$I_F=20mA$, $T_A=25^\circ C$	0.37	
	V_F	V	$I_F=200mA$, $T_A=25^\circ C$	0.60	
Maximum Reverse current	I_R	μA	SD103AWS $V_R=30V$, $T_A=25^\circ C$	5.0	
			SD103BWS $V_R=20V$, $T_A=25^\circ C$		
			SD103CWS $V_R=10V$, $T_A=25^\circ C$		
Minimum Breakdown voltage	$V_{(BR)}$	V	$I_R=100\mu A$	SD103AWS	40
				SD103BWS	30
				SD103CWS	20
Typical Junction capacitance	C_J	pF	$V_R=0V$, $f=1MHz$	50	



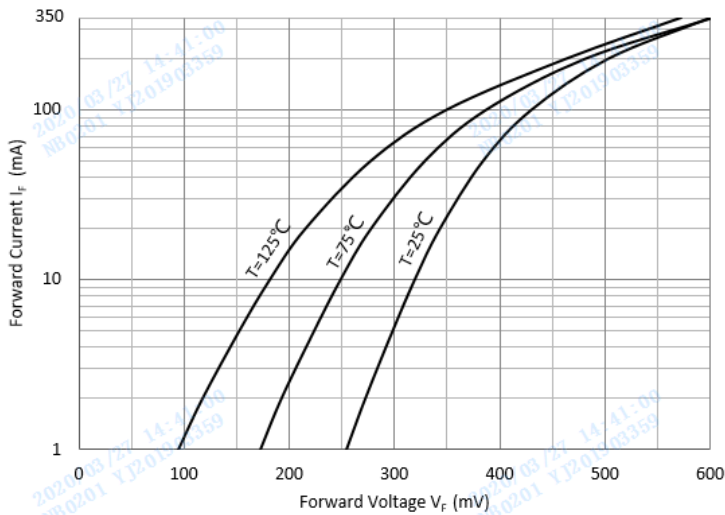
SD103AWS THRU SD103CWS

■ Ordering Information (Example)

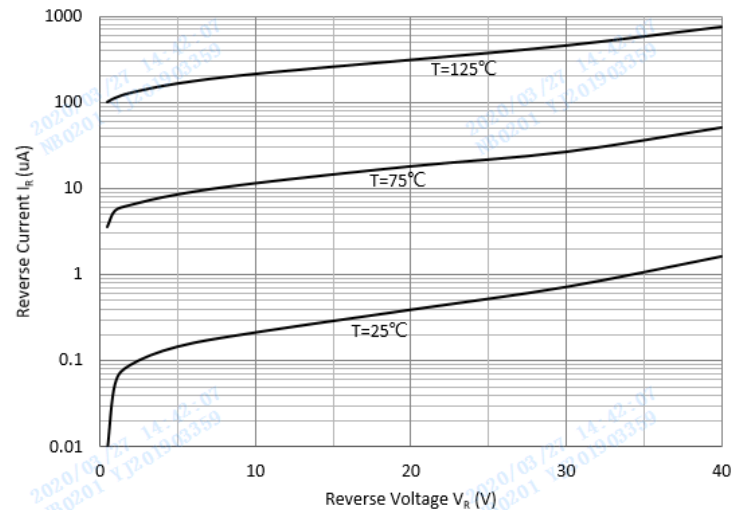
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SD103AWS Thru SD103CWS	F2	Approximate 0.0048	3000	30000	120000	7" reel

■ Characteristics (Typical)

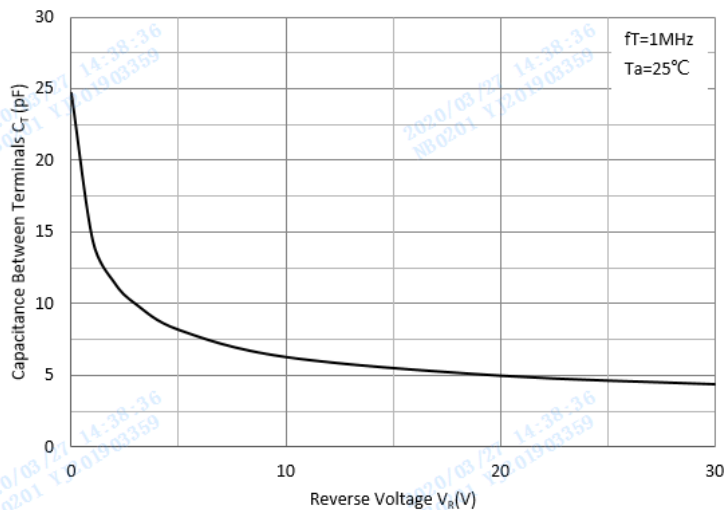
Forward Characteristics



Reverse Characteristics



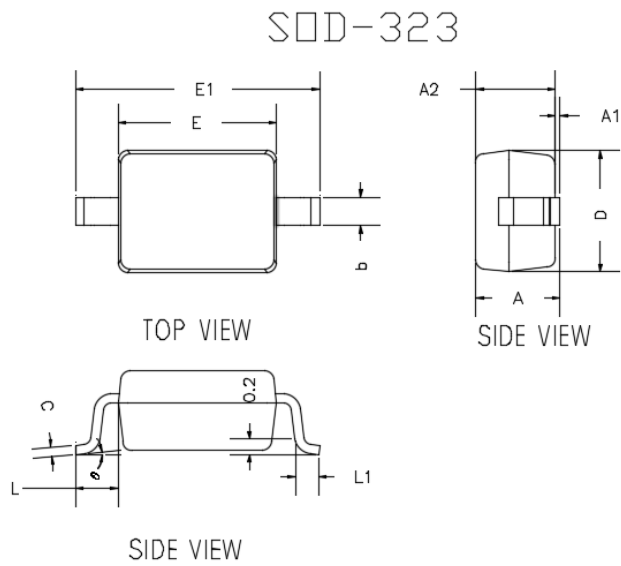
Capacitance Characteristics





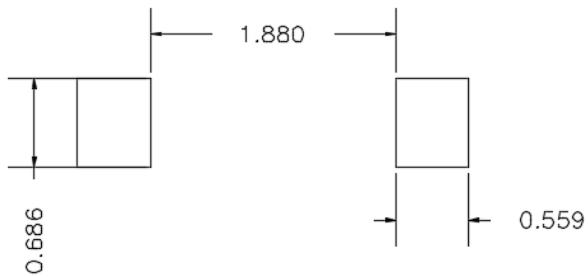
SD103AWS THRU SD103CWS

■ Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

■ Soldering Footprint



UNIT : mm

SUGGESTED SOLDER PAD LAYOUT



SD103AWS THRU SD103CWS

Disclaimer

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